

MID Selective Metallization

Plating Solutions for Molded Interconnect Devices

Expand Your Design Palette. Expand Your Opportunities.

MacDermid Enthone **Molded Interconnect Devices (MID)** plating solutions are specifically designed and optimized to deliver precise selectivity, high yields, and ease-of-use for laser direct structured, catalytic ink, and double-shot molded interconnect devices. Delivering consistent selectivity on a wide variety of materials and catalysts, our copper, nickel, gold, and silver plating solutions enable more complex and efficient designs on the most desirable and low cost molding composites. Simple and controllable processes result in steady plating rates coupled with long and predictable bath performance.

MID applications are rapidly expanding into new and exciting areas in electronics applications. Once a mainstay in mobile devices, increasing opportunities are now spreading within the medical, automotive, and lighting industries. As these opportunities expand, new materials are being considered to address physical properties and costs related to the application.



KEY FEATURES

- Unmatched selectivity on laser direct structured materials
- Highest yields on all current and emerging plastics
- Stable, long-lasting, easy-to-use chemical processes
- High tech applications in fine pitch plating and wire bonding



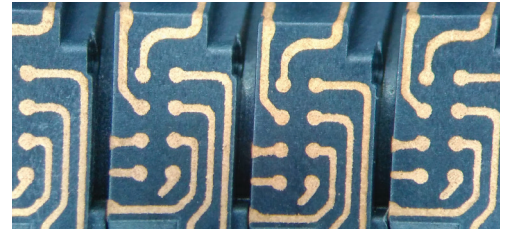
CIRCUITRY SOLUTIONS

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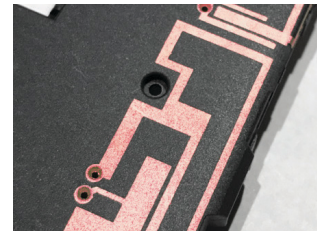
LDS SELECTCOAT 100 FL

As the applications for molded interconnect devices have expanded from simple large antennae constructions to advanced electronic devices, conductor line sizes have become an issue due to laser debris deflection leading to extraneous bridging during electroless deposition. **LDS Selectcoat 100 FL** completely solves this issue by acting as a sacrificial layer which can be removed from the part after laser direct structuring, leaving behind a pristine surface between LDS traces, allowing for compact design with finer geometries.



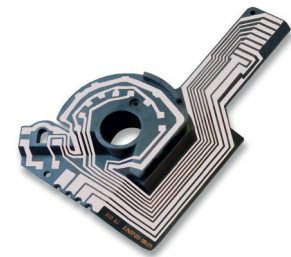
MID COPPER 100

MacDermid Enthone's **MID Copper 100** processes provide the industry leading electroless copper metallization for molded interconnect devices. Developed from a long history of premium electroless copper processes and backed by a global chemical service company, MID Copper 100 is the electroless copper process that is specified by OEMs and tier ones when they demand quality and reliability. All MID Coppers are formulated to provide superior stability and performance, enabling maximum process yields.



ENPLATE® LDS NI 200

ENPLATE® LDS NI 200 is a medium phosphorus electroless nickel deposit that provides a robust barrier layer against environmental corrosion and electromigration. ENPLATE LDS NI 200 is part of a best process sequence for plating electroless nickel/immersion gold (ENIG) and electroless nickel/electroless palladium/immersion gold (ENEPIG) on molded interconnect devices. These barrier layers allow for advanced assembly, including flip chip and gold wirebonding.



ENPLATE LDS AG 600

ENPLATE® LDS AG 600 is an alternative to electroless nickel/immersion gold (ENIG) final finishes. ENPLATE LDS AG 600 is the preferred immersion silver process used by fabricators and specified by OEMs worldwide. The patented silver deposit provides a tarnish resistant finish and a reliable solder joint connection, meeting all MID final finish requirements.



macdermidalpha.com

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